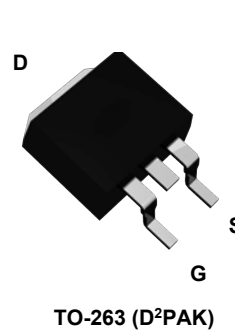
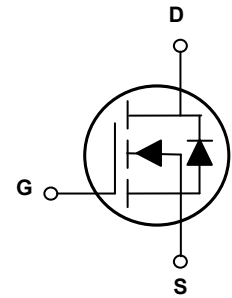


### Main Product Characteristics

$BV_{DSS}$	100V
$R_{DS(ON)}$	3.4m $\Omega$
$I_D$	175A



TO-263 (D<sup>2</sup>PAK)



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFT10176 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	175	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		110	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	700	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	1250	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	50	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	290	W
Power Dissipation-De-rate above 25 $^\circ\text{C}$		2.32	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.43	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^\circ\text{C}$

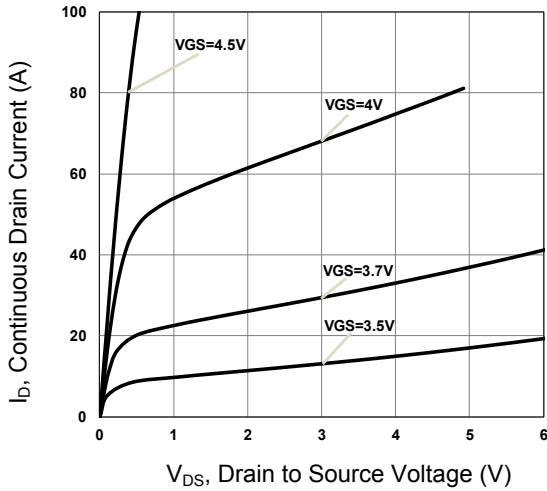
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1	$\mu A$
		$V_{DS}=80V, V_{GS}=0V, T_J=85^\circ\text{C}$	-	-	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	2.8	3.4	m $\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2	2.7	4	V
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=3A$	-	18	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=50V, I_D=80A, V_{GS}=10V$	-	92	135	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	19	30	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	27	40	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=50V, R_G=6\Omega, V_{GS}=10V, I_D=80A$	-	20	30	nS
Rise Time <sup>3,4</sup>	$t_r$		-	15	23	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	60	90	
Fall Time <sup>3,4</sup>	$t_f$		-	130	195	
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V, F=1\text{MHz}$	-	5600	8400	pF
Output Capacitance	$C_{oss}$		-	1200	1800	
Reverse Transfer Capacitance	$C_{rss}$		-	6	9	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	2	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	175	A
Pulsed Source Current	$I_{SM}$		-	-	350	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	-	-	1	V
Reverse Recovery Time	$t_{rr}$	$V_R=100V, I_S=10A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$	-	210	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	600	-	nC

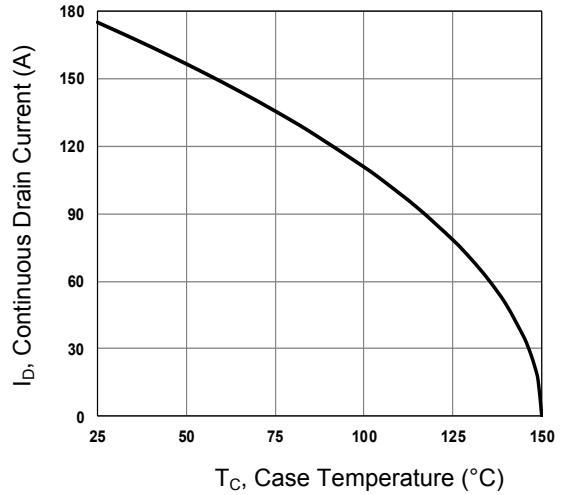
Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=50V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=50A, R_G=25\Omega, \text{starting } T_J=25^\circ\text{C}$ .
3. Pulse test: pulse width  $\leq 300\mu s, \text{duty cycle} \leq 2\%$ .
4. Essentially independent of operating temperature.

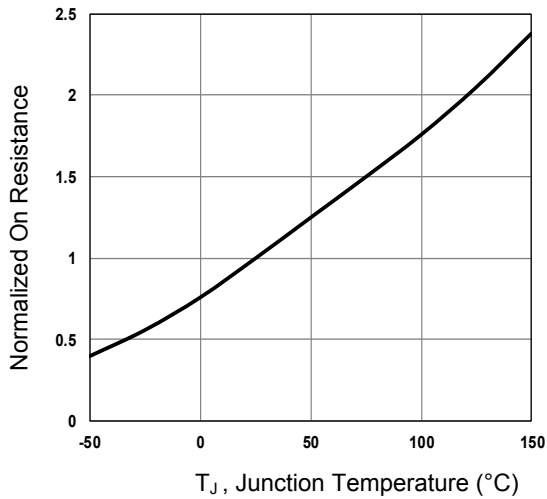
**Typical Electrical and Thermal Characteristic Curves**



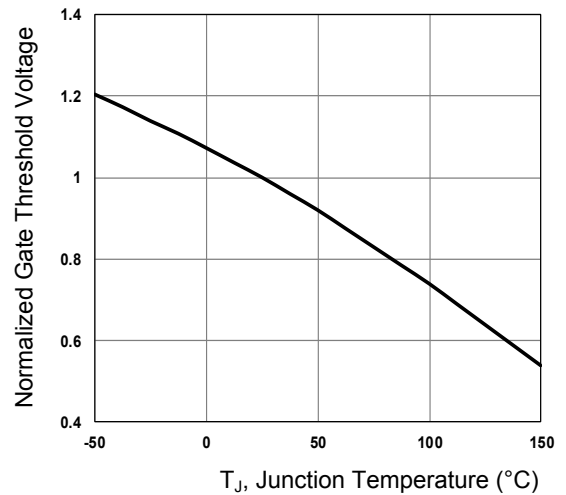
**Figure 1. Typical Output Characteristics**



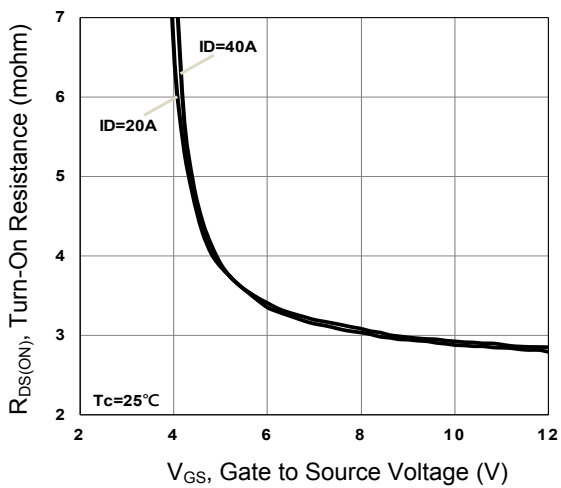
**Figure 2. Continuous Drain Current vs.  $T_C$**



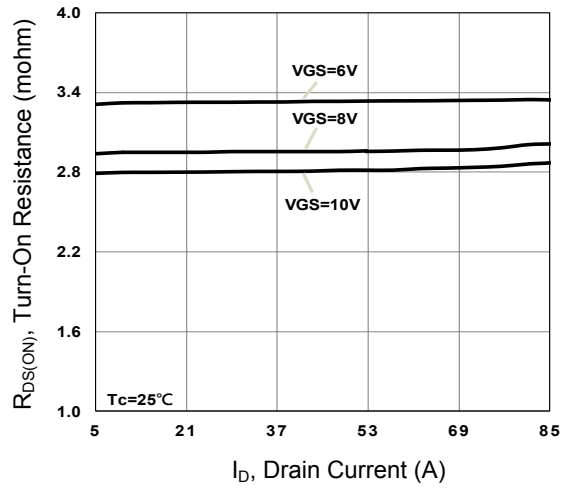
**Figure 3. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



**Figure 4. Normalized  $V_{th}$  vs.  $T_J$**

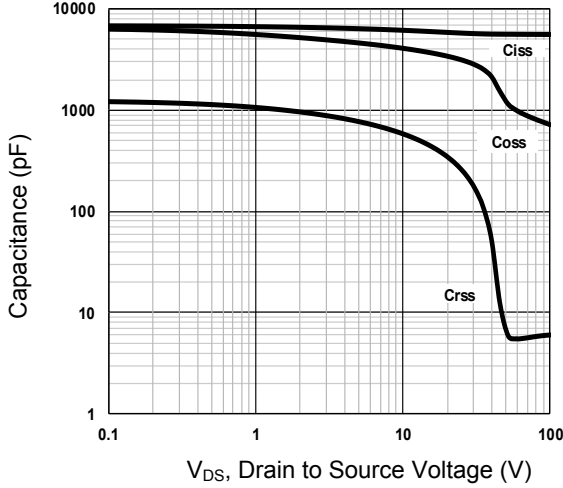


**Figure 5. Turn-On Resistance vs.  $V_{GS}$**

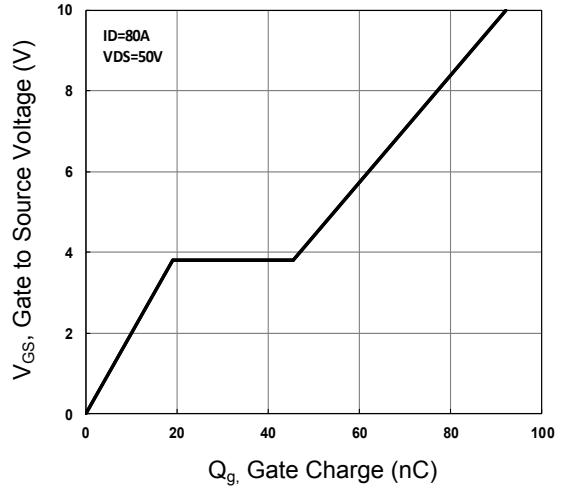


**Figure 6. Turn-On Resistance vs.  $I_D$**

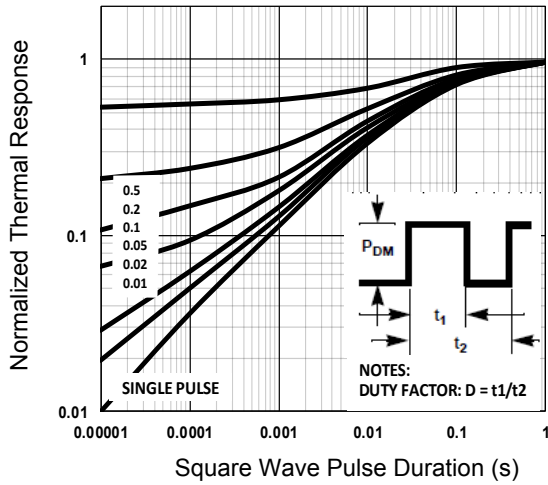
**Typical Electrical and Thermal Characteristic Curves**



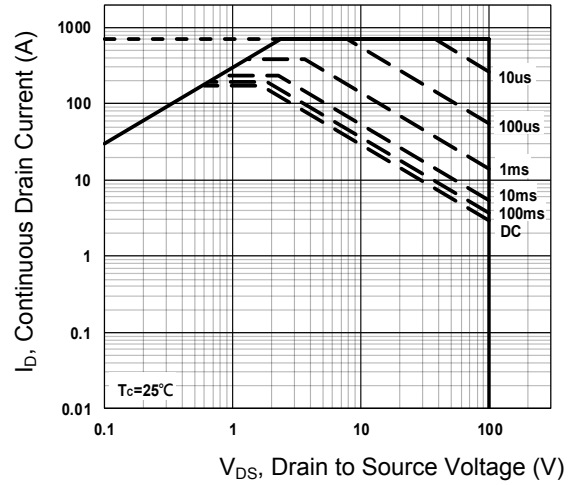
**Figure 7. Capacitance Characteristics**



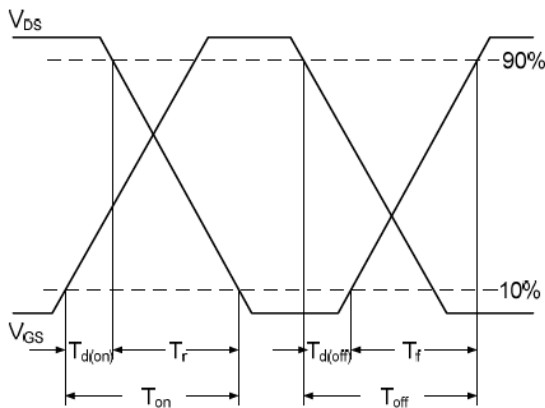
**Figure 8. Gate Charge Characteristics**



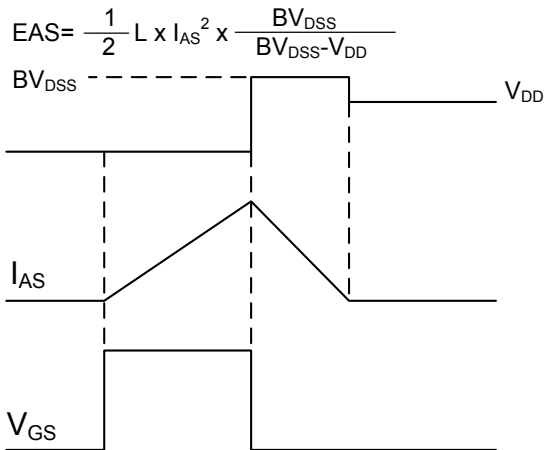
**Figure 9. Normalized Transient Impedance**



**Figure 10. Maximum Safe Operation Area**



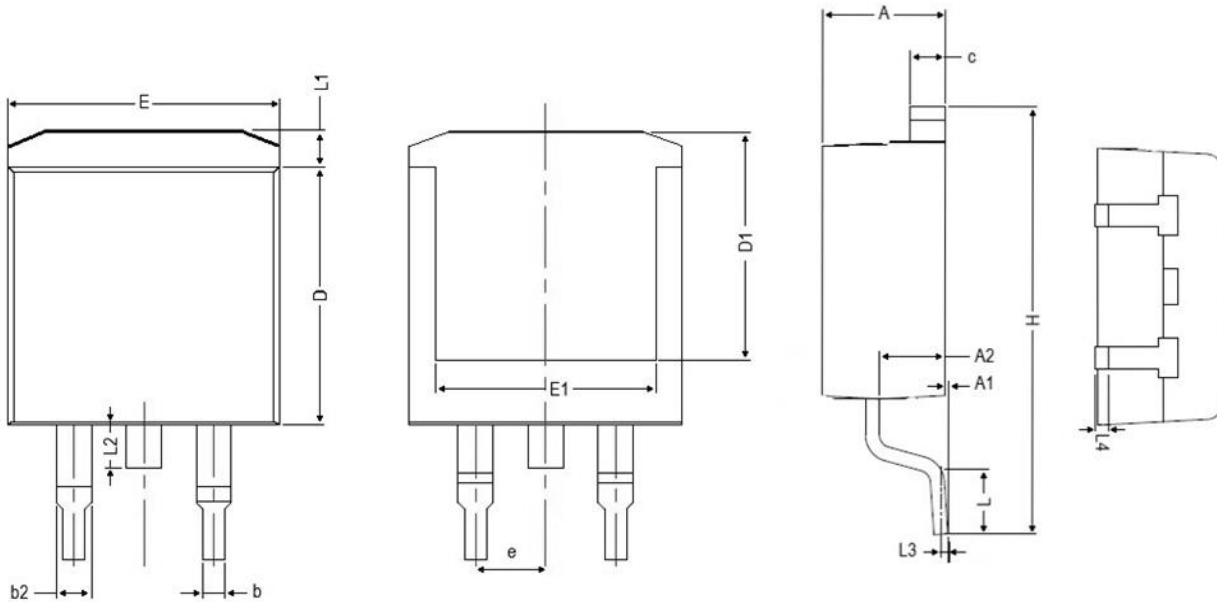
**Figure 11. Switching Time Waveform**



**Figure 12. EAS Waveform**

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

**Package Outline Dimensions (TO-263 D<sup>2</sup>PAK)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	4.850	4.250	0.191	0.167
A1	0.250	0.000	0.001	0.000
A2	2.900	2.350	0.114	0.093
b	0.950	0.700	0.037	0.028
b2	1.600	1.000	0.063	0.039
c	1.450	1.200	0.057	0.047
D	9.500	8.350	0.374	0.329
D1	9.150	6.400	0.360	0.252
E	10.500	9.600	0.413	0.378
E1	8.900	7.500	0.350	0.295
e	2.540 BSC		0.100 BSC	
H	15.900	14.600	0.626	0.575
L	2.800	2.000	0.110	0.079
L1	1.700	1.150	0.067	0.045
L2	2.100	1.400	0.083	0.055
L3	0.250 BSC		0.010 BSC	
L4	0.750	0.200	0.030	0.001